

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
- 60	0.066 at V <sub>GS</sub> = - 10 V	- 20	40 nC			
	$0.080$ at $V_{GS} = -4.5 \text{ V}$	- 18	40110			

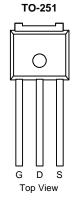
#### **FEATURES**

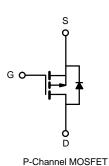
- TrenchFET® Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 60			
Gate-Source Voltage		V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		- 20 <sup>a</sup>		
Continuous Drain Current /T 450 °C)	T <sub>C</sub> = 70 °C		- 16		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 11 <sup>b</sup>		
	T <sub>A</sub> = 70 °C		- 9 <sup>b</sup>	Α	
Pulsed Drain Current	I <sub>DM</sub>	- 100			
Avalanche Current Pulse		I <sub>AS</sub>	- 35		
Single Pulse Avalanche Energy	L = 0.1 Min	E <sub>AS</sub>	101	mJ	
0 11 0 0 0 1	T <sub>C</sub> = 25 °C	1	- 29 <sup>a</sup>	^	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 2.1 <sup>b</sup>	A	
	T <sub>C</sub> = 25 °C		35 <sup>a</sup>		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	Б	20 <sup>a</sup>	10/	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.0 <sup>b</sup>	W	
	T <sub>A</sub> = 70 °C		2 <sup>b</sup>		
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	$R_{thJA}$	33	40	°C/W		
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.98	1.2	- °C/vv		

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		68		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = - 230 μΑ		- 5.2		] mv/·c	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valta da Busin Comunit		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
	<u> </u>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.066	1		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.080		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>	·				<u> </u>	·	
Input Capacitance	C <sub>iss</sub>			1200		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		200			
Reverse Transfer Capacitance	C <sub>rss</sub>			150			
Total Oata Ohamus	Qg	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = -10 V, I <sub>D</sub> = -55 A		40			
Total Gate Charge				38		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -55 \text{ A}$		16			
Gate-Drain Charge	$Q_{gd}$			19			
Gate Resistance	$R_{g}$	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = -2 \text{ V}, R_{L} = 2 \Omega$		7	15	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		70	110		
Fall Time	t <sub>f</sub>			40	60		
<b>Drain-Source Body Diode Characteristics</b>	5				L	l	
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 66	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 150		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	68	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			59	120	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -50 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		29			
Reverse Recovery Rise Time t <sub>b</sub>			16	16		ns	

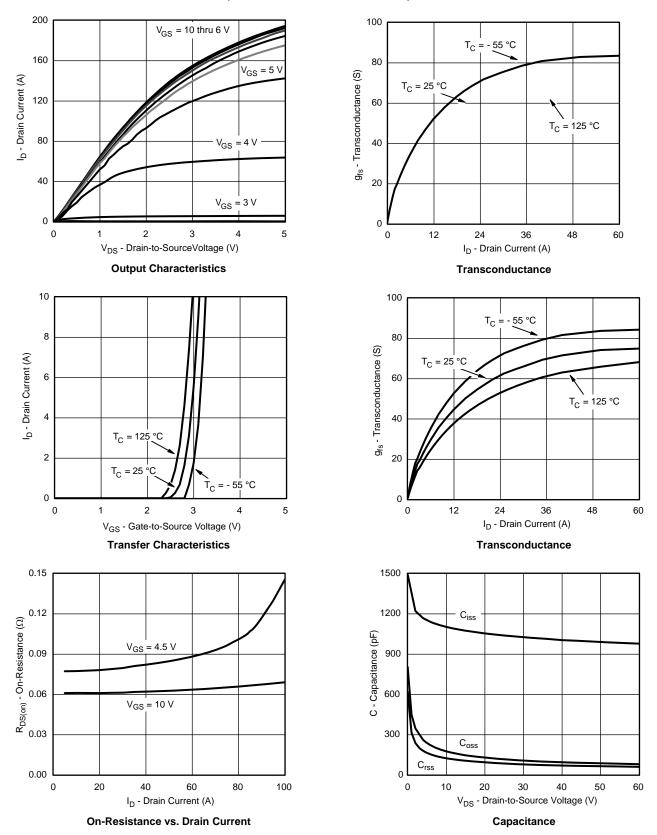
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

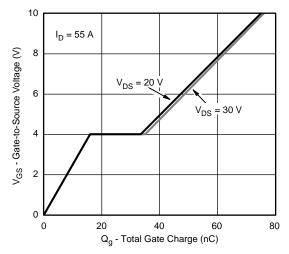


### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

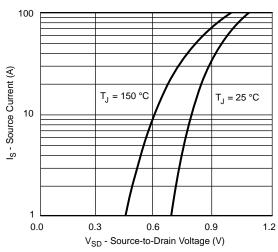




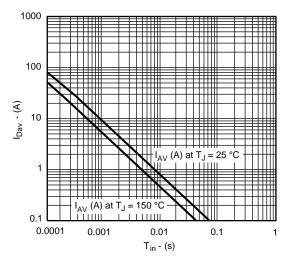
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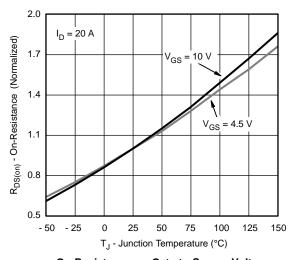




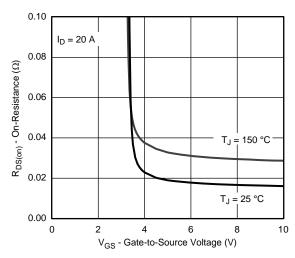
Source-Drain Diode Forward Voltage



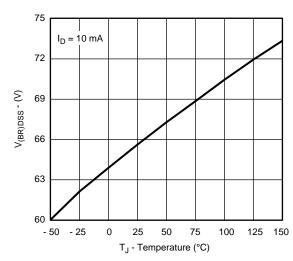
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



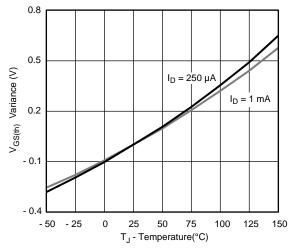
On-Resistance vs. Gate-to-Source Voltage

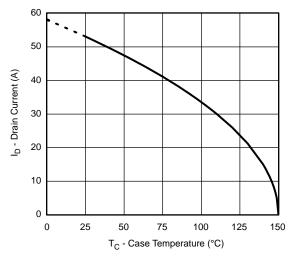


Drain-Source Breakdown Voltage vs. Junction Temperature

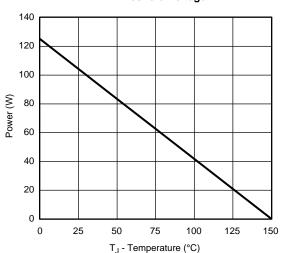


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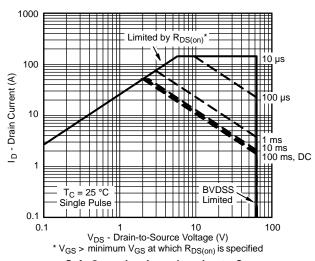




Threshold Voltage

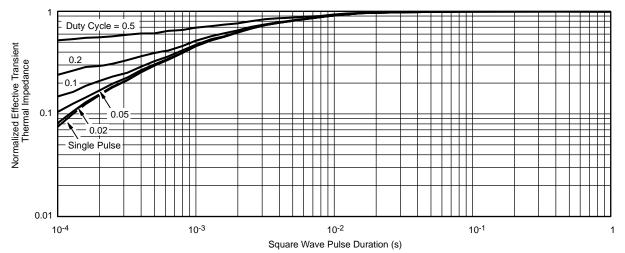


Max. Drain Current vs. Case Temperature



Power Derating, Junction-to-Case

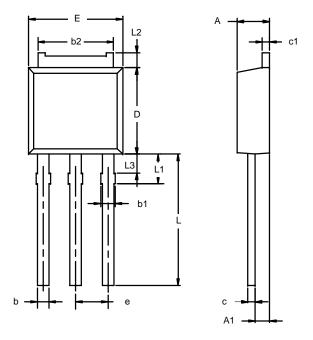




Normalized Thermal Transient Impedance, Junction-to-Case



### TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIM	ETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	8.89	9.53	0.350	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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